



SOT638-6

plastic thermal enhanced thin quad flat package; 100 leads;
exposed diepad, 0.5 mm pitch, 14 mm x 14 mm x 1 mm body

19 August 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFP100
Package type industry code	HTQFP100
Package style descriptive code	HTQFP (thermal enhanced thin quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	01-09-2009
Manufacturer package code	SOT638

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	13.9	14	14.1	mm
package width	13.9	14	14.1	mm
seated height	1	1.1	1.2	mm
package height	0.95	1	1.05	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	100	-	



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2 Package outline

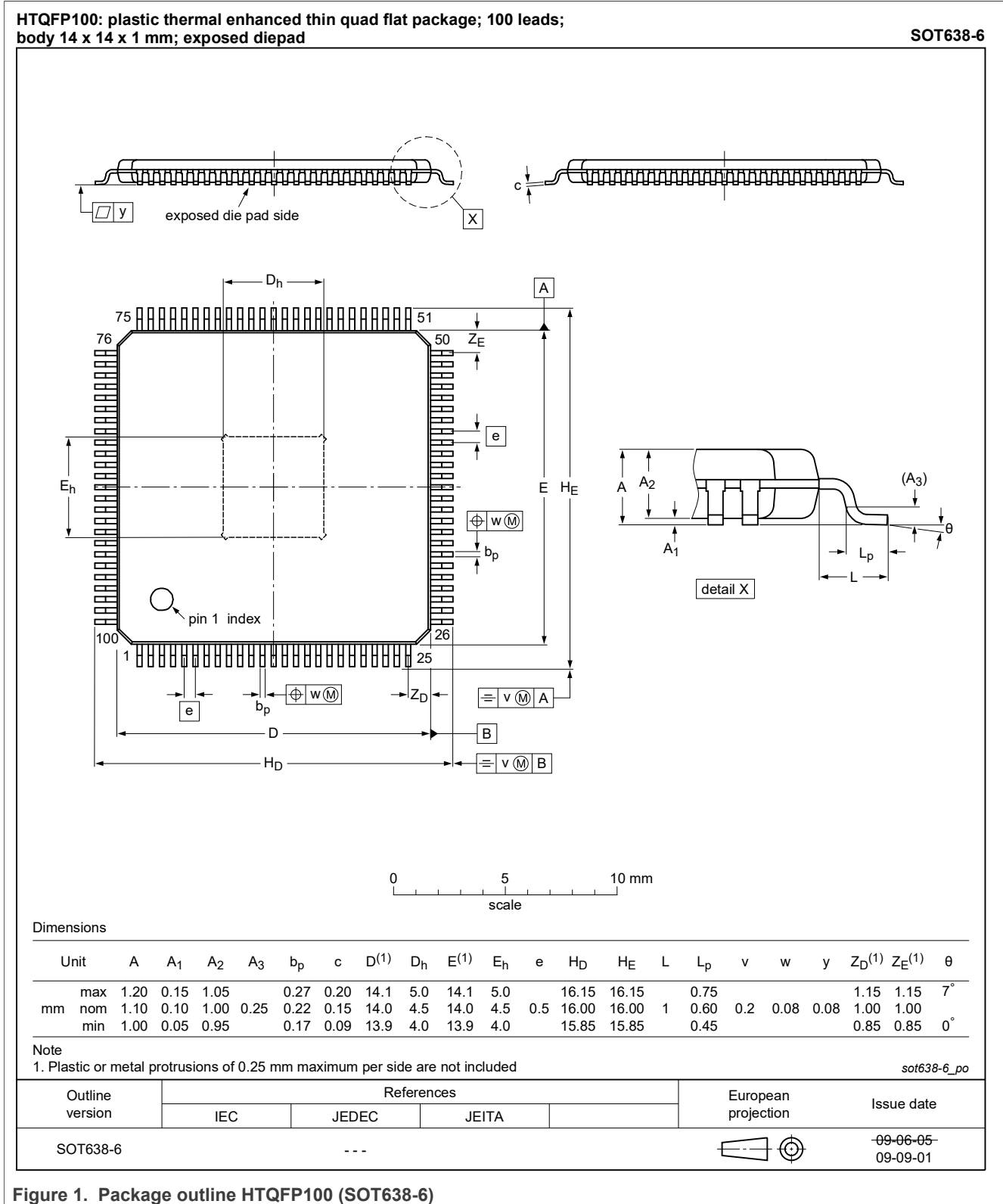


Figure 1. Package outline HTQFP100 (SOT638-6)

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3 Legal information

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